

Title (en)

METHOD OF CONNECTING CIRCUIT BOARDS AND CONNECTED STRUCTURE

Title (de)

VERFAHREN ZUR VERBINDUNG VON LEITERPLATTEN UND VERBUNDENE STRUKTUR

Title (fr)

PROCEDE DE CONNEXION DE CARTES DE CIRCUIT IMPRIME ET STRUCTURE CONNECTEE

Publication

EP 2084786 A1 20090805 (EN)

Application

EP 07844156 A 20071011

Priority

- US 2007081073 W 20071011
- JP 2006289932 A 20061025

Abstract (en)

[origin: WO2008051727A1] A method of connecting circuit boards capable of easily accomplishing the connection maintaining reliability. A method of connection comprising the steps of obtaining a laminated body of a first circuit board, an adhesive sheet and a second circuit board, and accomplishing electric conduction between the first circuit and the second circuit by applying heat and pressure to the laminated body of the first circuit board, the adhesive sheet and the second circuit board, wherein an end of the circuit formed on at least either the first circuit board or the second circuit board is terminated at a position separated away from an end of the substrate, and the adhesive of the adhesive sheet is partly arranged between the end of the substrate of the circuit board and the end of the circuit so as to be adhered to the opposing circuit board.

IPC 8 full level

H05K 3/36 (2006.01)

CPC (source: EP KR US)

H01R 4/04 (2013.01 - EP US); **H01R 12/52** (2013.01 - EP US); **H01R 12/61** (2013.01 - EP US); **H01R 12/71** (2013.01 - KR); **H01R 43/00** (2013.01 - KR); **H05K 3/361** (2013.01 - EP US); **H05K 3/305** (2013.01 - EP US); **H05K 2201/09245** (2013.01 - EP US); **H05K 2201/09381** (2013.01 - EP US); **H05K 2201/09427** (2013.01 - EP US); **H05K 2201/09709** (2013.01 - EP US); **H05K 2201/10977** (2013.01 - EP US); **H05K 2203/1189** (2013.01 - EP US); **Y10T 29/49126** (2015.01 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

WO 2008051727 A1 20080502; CN 101529662 A 20090909; EP 2084786 A1 20090805; EP 2084786 A4 20100120; JP 2008108890 A 20080508; KR 20090082370 A 20090730; TW 200830955 A 20080716; US 2011000700 A1 20110106

DOCDB simple family (application)

US 2007081073 W 20071011; CN 200780039881 A 20071011; EP 07844156 A 20071011; JP 2006289932 A 20061025; KR 20097008429 A 20071011; TW 96139947 A 20071024; US 44651807 A 20071011